

# SID

Factory: Rot am See

Article:

564

ML8

Provided:

Landwehr, Melanie

Customer:

Date:

15.12.2015



Processtechnology: B: undefiniert

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	B00
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	150		2	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		3	
C-RS-FR4-ML-0.41mm-070+070-TG150-HF	50200759	70	L2	4	
		410			
		70	L3		
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	160		5	
		0		6	
C-RS-FR4-ML-0.41mm-070+070-TG150-HF	50200759	70	L4	7	
		410			
		70	L5		
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	160		8	
		0		9	
C-RS-FR4-ML-0.41mm-070+070-TG150-HF	50200759	70	L6	10	
		410			
		70	L7		
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	150		11	
		0		12	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	13	

Thickness after Pressing

B00:

2290 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2530 µm

Dmin:

2050 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2400 µm

Tol+:

240 µm

Tol-:

240 µm

Dmax:

2640 µm

Dmin:

2160 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

2306 µm

Version 1.2.14.15

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